emerging respectively at the interface, so as to enable passage in the cavity of separation means; and wherein the process also involves, at separation, exertion of a force, in a localized manner at the interface, by application of the separation means, to initiate separation of the two elements starting at the interface, and to continue the separation process, if applicable, until complete separation of the two elements.

31. (New) A separation process in claim 30, in which the separation of the two elements is induced in one or more interfaces, in a simultaneous or sequential manner.

32. (New) A separation process in claim 30, wherein the separation means contains means for exerting a mechanical action at the interface.

33. (New) A separation process in claim 30, wherein the separation means contains means for exerting a fluid pressure at the interface.

34. (New) A separation process in claim 30, wherein the separation means contains means for exerting a chemical action on at least one of the elements at the interface.

35. (New) A separation process in claim 30, wherein the cavities are obtained by engraving.

36. (New) A separation process in claim 30, in which the adherence faces define at least one of interface zones, and in which the cavities are made at a periphery of at least one element, in the adherence faces.

37. (New) A separation process in claim 30, wherein the cavities are made in an inner region of at least one element, at the interface.

38. (New) A process in claim 30, wherein at least one cavity penetrates through at least one element from side to side.

39. (New) A separation process in claim 30, wherein, where several interface zones are planned and are arranged so as to initiate the separation at determined locations of the interface.

40. (New) A separation process in claim 37, wherein, with the fluid being a liquid fluid, the separation means involve microwave excitation of the liquid fluid.

41. (New) A separation process in claim 30, wherein the two elements adhere to one another with a different adherence energy in different regions of an adherence interface between the elements, so as to initiate separation at a determined location of the adherence interface.

42. (New) A separation process in claim 30, for separating two elements of a structure having at least a first interface formed at the adherence faces of the two elements, and at least one second interface formed in at least one of the elements, in which a separation of the structure is induced at one of the first and second interfaces.

43. (New) A separation process in claim 42, for the separation of a structure with a bonding energy in the second interface lower than a bonding energy of the first interface, in which a separation of the structure in the second interface is induced.

44. (New) A separation process in claim 42, in which, before the two elements are brought into contact, an embrittled zone is formed in at least one of the two elements forming the second interface.

45. (New) A separation process in claim 44, in which the embrittled zone is formed using an implantation technique or using a layer adherence technique.

46. (New) A separation process in claim 45, in which the embrittled zone is formed at a shallow depth in one of the elements such that the second interface delimits a thin layer in the element.

47. (New) A device for separating two elements of a structure, adhering to one another by adherence faces at least one of which has cavities in an interface zone so as to be configured to subject at least one of the adherence faces to influence of at least one of a fluid and a mechanical action, where the device contains an enclosure with at least one high-pressure chamber, configured to receive the fluid, and at least one low-pressure chamber, and where the enclosure is formed so as to receive the two adherent elements such that the cavities communicate with the high-pressure chamber.

48. (New) A separation device in claim 47, further comprising means for forming a stop on occurrence of deformation judged to be excessive of at least one of the two elements of the structure when they are separated.

49. (New) A separation device in claim 47, wherein the means for holding the structure contain at least one joint arranged between an element of the structure and a wall of the enclosure.

50. (New) A separation device in claim 49, in which at least one joint is arranged between a main face of at least one element in a form of a plate and a wall of the enclosure facing the main face.

51. (New) A separation device in claim 49, in which at least one joint is arranged between an edge of at least one element in a form of a plate and a wall of the enclosure facing the edge.

52. (New) A handle for transferring objects including an adherence face with cavities in at least some interface zones, and to which objects can adhere, and including means of access to interface zones in order to separate the objects.

53. (New) A transfer handle in claim 52, including a plate, one face of which constitutes the adherence face, and where the plate is pierced with holes which penetrate

through, emerging at the interface zones and constituting the means of access to the interface zones.

54. (New) A transfer handle in claim 53, wherein the penetrating holes are holes allowing a tool for separating the objects to pass through.

55. (New) A transfer handle in claim 52, wherein the means of access to the interface zones are channels for application of a pressurized fluid.

56. (New) A transfer handle in claim 55, containing channels for application of a fluid made in the adherence face and formed according to a concentric circle pattern, a spiral pattern, a radial pattern, or a diagonal intersecting pattern between sectors of the adherence face.

57. (New) A transfer handle in claim 55, in which the channels constitute at least one of cavities and link cavities made in the adherence face.

58. (New) A process for transferring objects made on a surface of a first substrate, where the objects have an adherence face, and the process comprises the following stages:

adherence faces of one or more objects are brought into contact with the adherence face of a transfer handle in claim 50,

possibly, the first substrate is thinned on a free face of the first substrate,

at least one of the objects is brought into adherent contact with a receiving substrate,

the object is separated from the handle.